

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No.09/468,247
 Priority Filing Date12/20/99
 Inventor.....Perino et al.
 Applicant Rambus, Inc.
 Priority Group Art Unit2833
 Priority Examiner Paumen
 Attorney's Docket No.RB1-035USC3
 Title: Chip Socket Assembly and Chip File Assembly for Semiconductor Chips

INFORMATION DISCLOSURE STATEMENT

The citations listed are submitted in compliance with the duty of disclosure defined in 37 CFR §1.56. Copies of the cited references were cited or submitted with the priority application and are therefore not submitted herewith.

The Examiner is requested to make these citations of official record in this application.

Respectfully Submitted,

Date: 9/20/01

By: Daniel L. Hayes
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